Open-molded Plastic Packages (OmPP)

Air Cavity QFN Packages
Open-molded Plastic Packages (OmPP) are pre-molded air cavity plastic QFN/SOIC packages designed to provide a convenient high-quality, high-performance solution for your prototype to full-production needs. Over 35 designs in multiple thicknesses, with a variety of pitch options and lead frame composition alternatives, are available immediately. Package turn times as fast as one day, with three to five days standard.

- 3x3 mm to 12x12 mm QFN package sizes
- Custom DFN/QFN body sizes and lead counts
- Ni/Au-plated lead frames standard; Ni/Pd/Au available
- Superior bondability
- Larger die-paddle area supports large die and ground bonds, per body size
- RoHS- and REACH-compliant “Green” molding compound

Pre-Molded Air Cavity QFN Packages
- Quality suitable for production applications
- Same-day availability on most options
- Performance realized into the Ka band
- Largest selection of 0.4mm pitch packages
- Production volumes
- Mid-volume assembly services

Custom QFN Plastic Packages
- I/O or paddle pattern packages with low NRE charge
- 3mm-square DFNs and other configurations
- Packages built to your spec or design for specific applications, i.e. simulating package designs with high-frequency transmission lines
- Lead frame options for non-magnetic or low CTE applications
- Mold material options optimized for application

QFN Package Air Cavity Lids
- Standard flat lids made from 91% alumina ceramic
- Flat, RoHS- and REACH-compliant plastic lids
- Lid with B-stage epoxy ring for sealed IC packages
- Glass and quartz lids optional

Additional Packages
- Open cavity plastic packages (OcPP) for new IC prototypes
- Custom air cavity packages and plastic overmolded packages

Quick-Turn Assembly Services
- High-volume die attach
- Wire bonding
- Encapsulation
- Flip chip for BGAs, sensors, MEMS and chip-on-board devices

Wafer Prep Services
- Dicing
- Backgrinding
- Pick-and-place
### Quik-Pak QFN Package Sizes

<table>
<thead>
<tr>
<th>Body Width</th>
<th>Lead Count</th>
<th>Lead Pitch</th>
<th>DAP Size (sq)</th>
</tr>
</thead>
<tbody>
<tr>
<td>QP-QFN8-3mm-0.65mm</td>
<td>8</td>
<td>0.65mm</td>
<td>1.46mm</td>
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<td>3x3mm</td>
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<td>3x3mm</td>
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</table>

QP-SOIC-150
(Leaded 50-8)
8
100mm x 75mm

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Quik-Pak is a division of **Promex Industries**. Promex provides microelectronics assembly services from its 30,000-sq.ft. Silicon Valley facility, including Class 100/1000 cleanrooms for production of medical and biotech devices. The company offers advanced package design and materials consulting. Onsite scalable services include heterogeneous assembly, RoHS-optimized SMT, wafer thinning, dicing, wirebond, flip chip and overmolding. Promex also holds a CA FDB license to manufacture Class II and Class III medical devices. Promex can be reached by calling 1-408-496-0222 or visiting www.promex-ind.com.

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